



- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

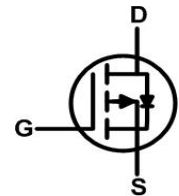
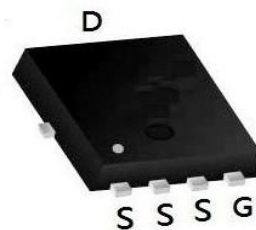
**Product Summary**

BVDSS	RDSON	ID
85V	4.3mΩ	100A

**Description**

The XXWS100N85F is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The XXWS100N85F meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

**PRPAK5X6 Pin Configuration**

**Absolute Maximum Ratings (T<sub>A</sub> = 25°C, unless otherwise noted)**

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V <sub>DS</sub>	85	V
Gate-Source Voltage		V <sub>GS</sub>	±20	V
Continuous Drain Current	T <sub>C</sub> =25°C	I <sub>D</sub>	100	A
	T <sub>C</sub> =100°C		63.3	
Pulsed Drain Current <sup>1</sup>		I <sub>DM</sub>	400	A
Single Pulse Avalanche Energy <sup>2</sup>		EAS	273.8	mJ
Total Power Dissipation	T <sub>C</sub> =25°C	P <sub>D</sub>	107.8	W
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	R <sub>θJA</sub>	60	°C/W
Thermal Resistance from Junction-to-Case	R <sub>θJC</sub>	1.16	°C/W

**Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	85	-	-	V
Gate-body Leakage current	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$T_J=25^\circ\text{C}$	$V_{DS} = 85V, V_{GS} = 0V$	-	-	1	$\mu A$
	$T_J=100^\circ\text{C}$		-	-	100	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	3	4	V
Drain-Source on-Resistance <sup>4</sup>	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$	-	4.3	5.6	m $\Omega$
Forward Transconductance <sup>4</sup>	$g_{fs}$	$V_{DS} = 5V, I_D = 20A$	-	57.8	-	S
<b>Dynamic Characteristics<sup>5</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 40V, V_{GS} = 0V, f = 1\text{MHz}$	-	4645	-	$\mu F$
Output Capacitance	$C_{oss}$		-	673	-	
Reverse Transfer Capacitance	$C_{rss}$		-	41	-	
Gate Resistance	$R_g$	$f = 1\text{MHz}$	-	2.0	-	$\Omega$
<b>Switching Characteristics<sup>5</sup></b>						
Total Gate Charge	$Q_g$	$V_{GS} = 10V, V_{DS} = 40V, I_D = 20A$	-	61.3	-	nC
Gate-Source Charge	$Q_{gs}$		-	21	-	
Gate-Drain Charge	$Q_{gd}$		-	11	-	
Turn-on Delay Time	$t_{d(on)}$	$V_{GS} = 10V, V_{DD} = 40V, R_G = 3\Omega, I_D = 20A$	-	16.5	-	ns
Rise Time	$t_r$		-	51.8	-	
Turn-off Delay Time	$t_{d(off)}$		-	37.1	-	
Fall Time	$t_f$		-	8.2	-	
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = 20A, di/dt = 100A/\mu S$	-	69	-	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	141	-	nC
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{SD}$	$I_S = 20A, V_{GS} = 0V$	-	-	1.2	V
Continuous Source Current	$T_C=25^\circ\text{C}$	$I_S$	-	-	100	A

**Notes:**

1. Repetitive rating, pulse width limited by junction temperature  $T_J(\text{MAX})=150^\circ\text{C}$
2. The EAS data shows Max. rating . The test condition is  $V_{DD}=50V, V_{GS}=10V, L=0.4\text{mH}, I_{AS}=37A$
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
5. This value is guaranteed by design hence it is not included in the production test.

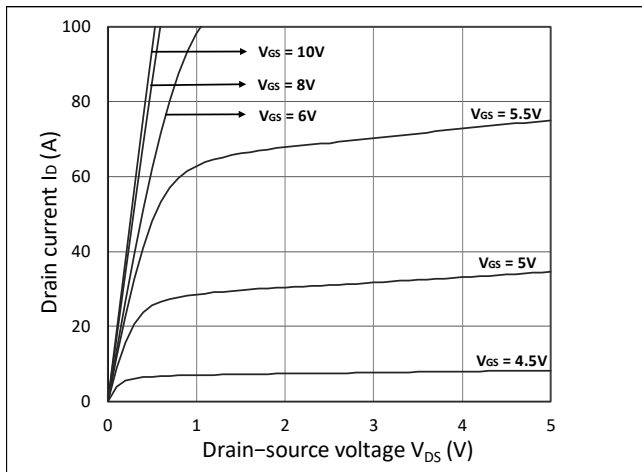
**Typical Characteristics**


Figure 1. Output Characteristics

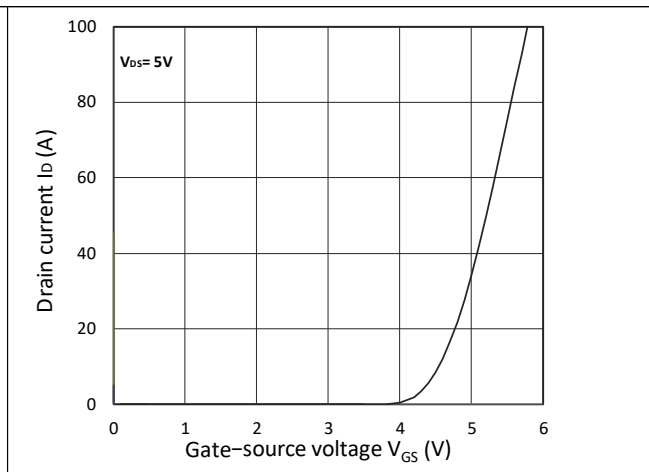


Figure 2. Transfer Characteristics

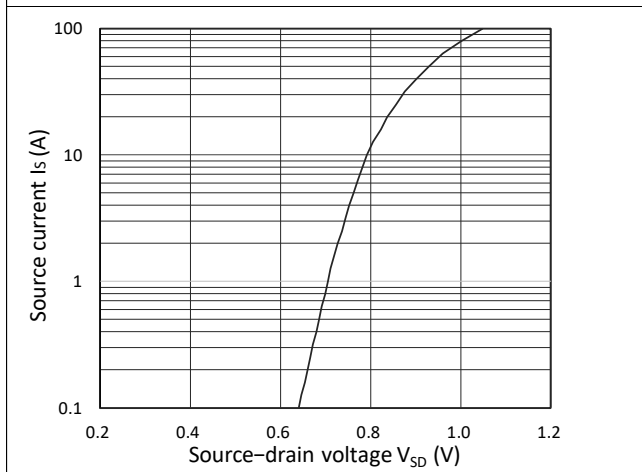
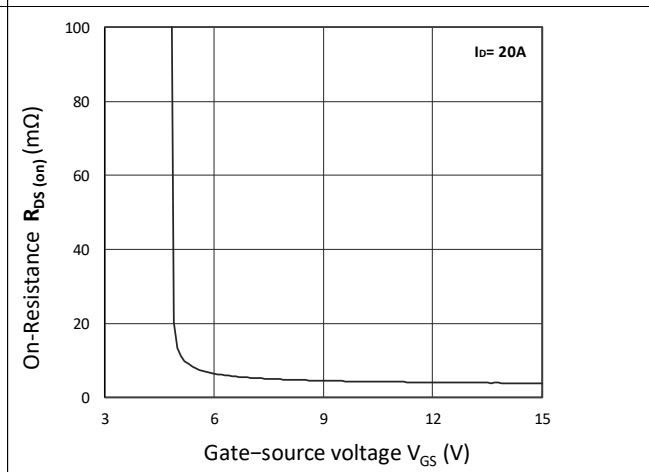
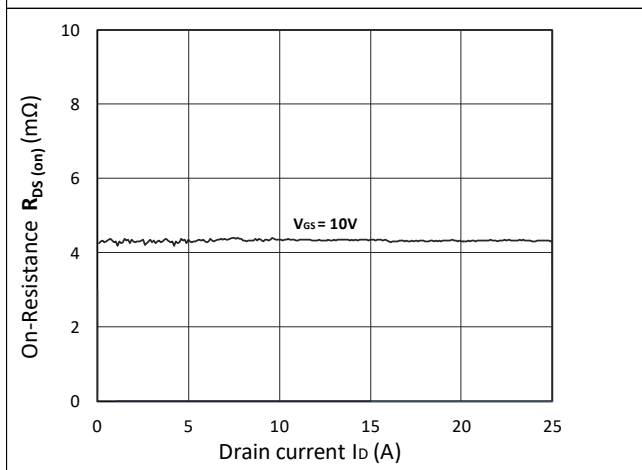
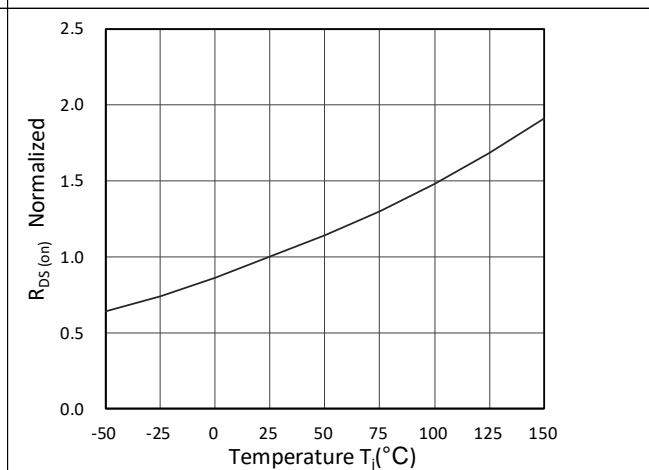


Figure 3. Forward Characteristics of Reverse


 Figure 4.  $R_{DS(ON)}$  vs.  $V_{GS}$ 

 Figure 5.  $R_{DS(ON)}$  vs.  $I_D$ 

 Figure 6. Normalized  $R_{DS(ON)}$  vs. Temperature

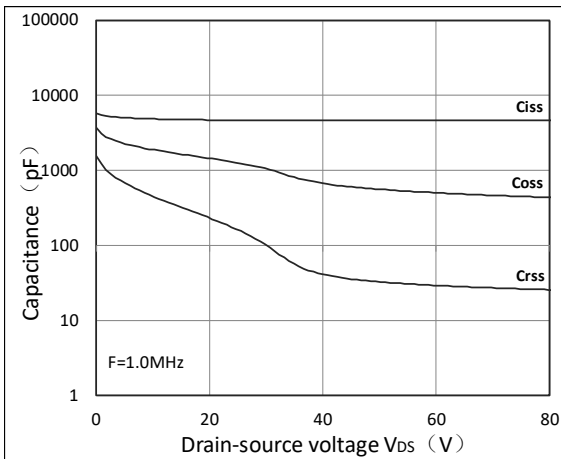


Figure 7. Capacitance Characteristics

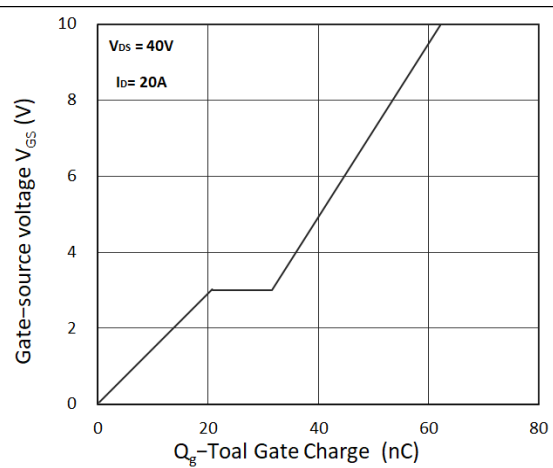


Figure 8. Gate Charge Characteristics

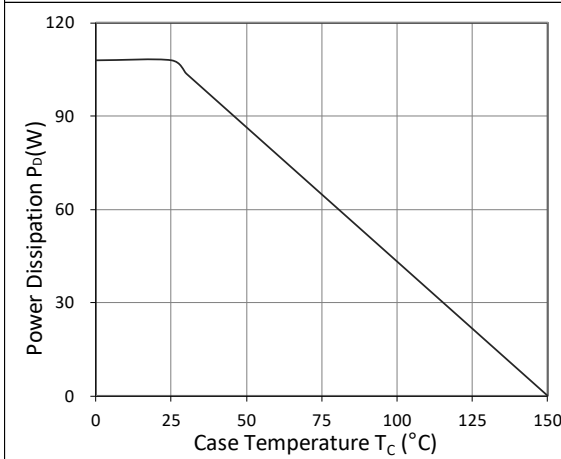


Figure 9. Power Dissipation

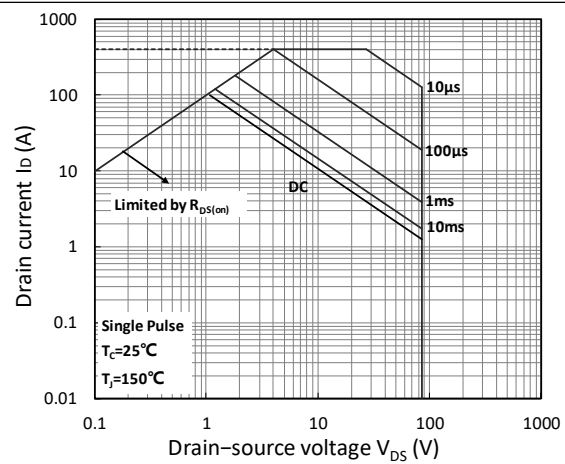


Figure 10. Safe Operating Area

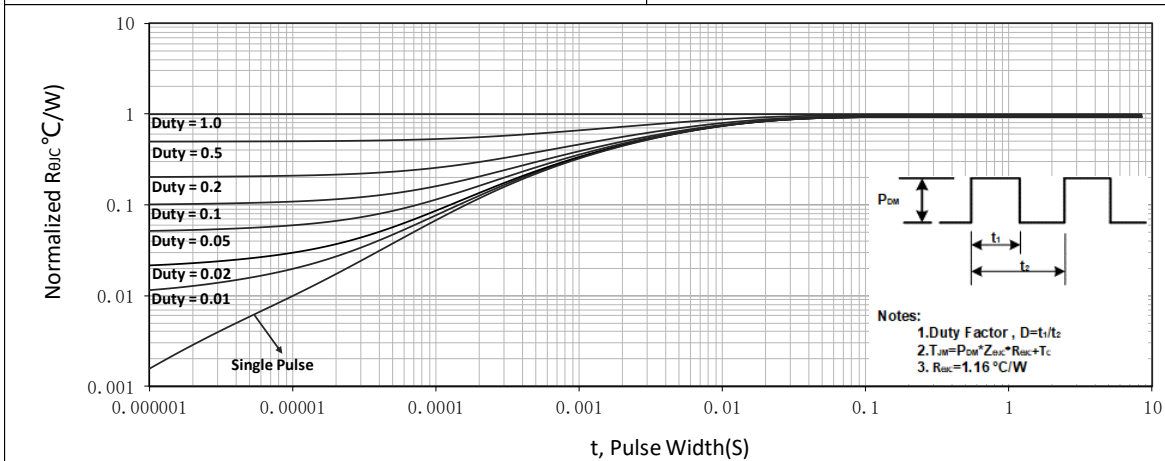
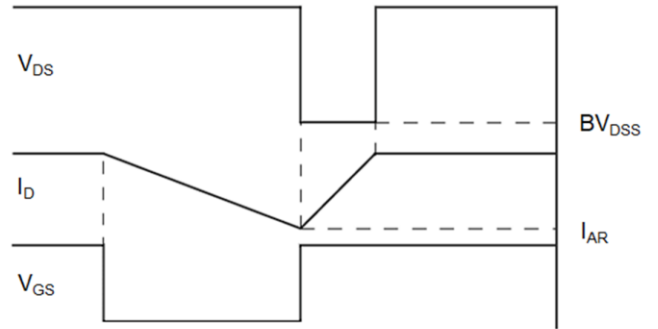
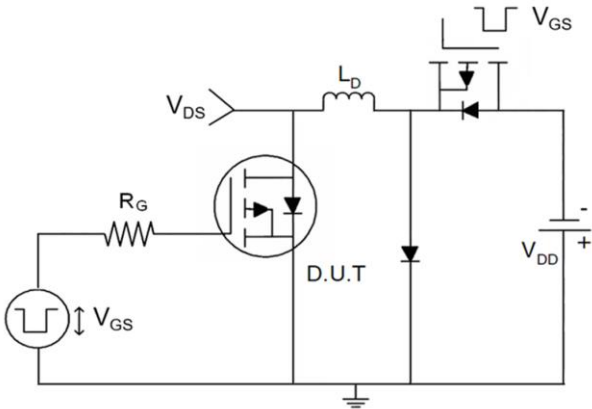
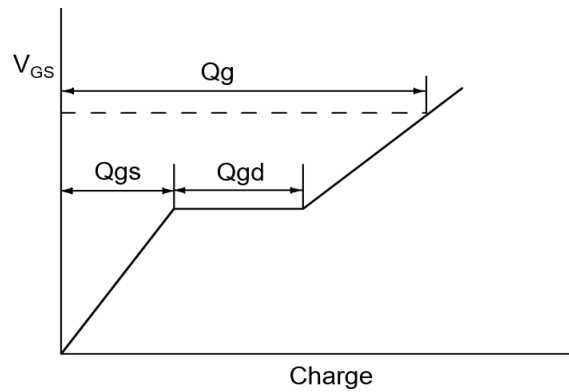
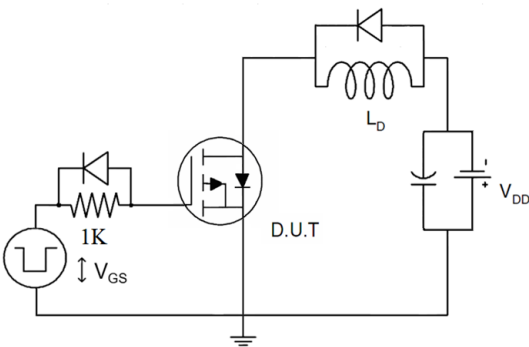


Figure 11. Normalized Maximum Transient Thermal Impedance

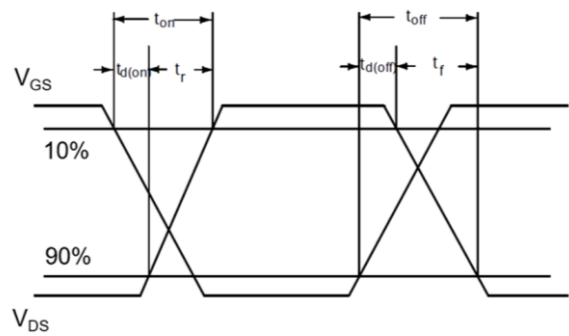
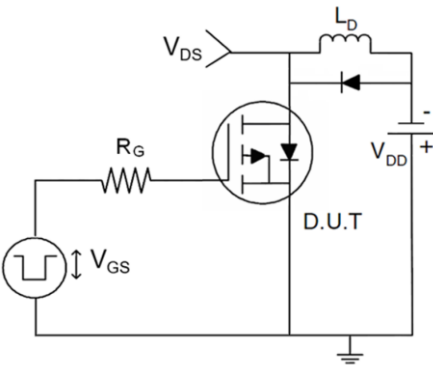
**1)  $E_{AS}$  Test Circuits**

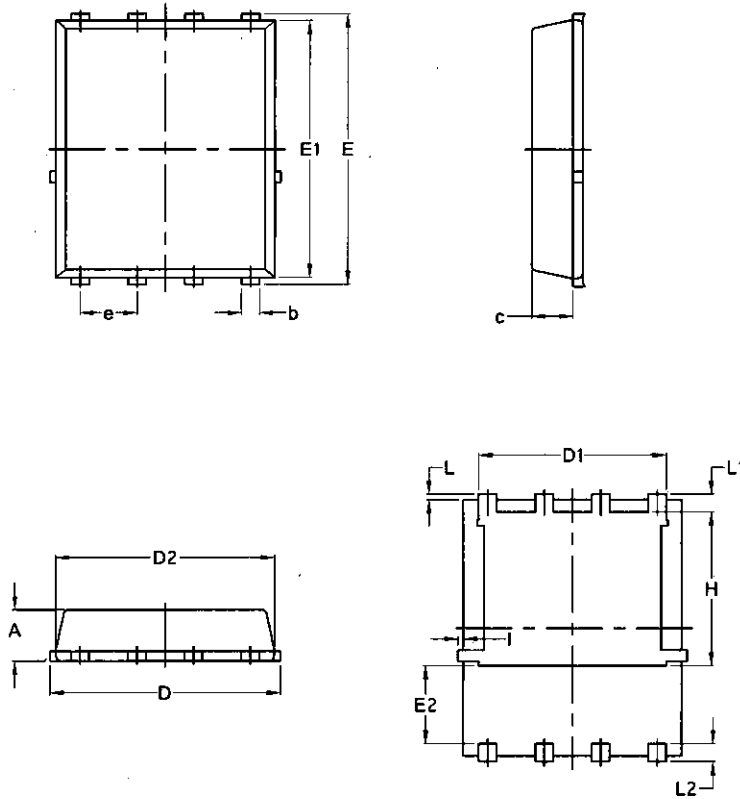


**2) Gate Charge Test Circuit**



**3) Switch Time Test Circuit**



**Package Mechanical Data-DFN5\*6-8L -Single**


Symbol	Common			
	mm		Inch	
	Min	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070